

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC118N10NS G	**Issued**	11. May 2021
MA#	MA001638960		
Package	PG-TDSON-8-39	**Weight***	113.74 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.666	3.22	3.22	32233	32233
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		128	
	non noble metal	iron	7439-89-6	0.049	0.04		428	
	non noble metal	copper	7440-50-8	48.649	42.78	42.83	427711	428267
wire	non noble metal	copper	7440-50-8	0.033	0.03	0.03	293	293
encapsulation	organic material	carbon black	1333-86-4	0.079	0.07		695	
	plastics	epoxy resin	-	6.247	5.49		54917	
	inorganic material	silicondioxide	60676-86-0	33.209	29.20	34.76	291966	347578
leadfinish	non noble metal	tin	7440-31-5	1.520	1.34	1.34	13364	13364
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1393	1393
solder	non noble metal	tin	7440-31-5	0.061	0.05		534	
	noble metal	silver	7440-22-4	0.076	0.07		667	
	non noble metal	lead	7439-92-1	2.899	2.55	2.67	25490	26691
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	noble metal	silver	7440-22-4	0.150	0.13		1319	
	non noble metal	copper	7440-50-8	16.910	14.87	15.01	148668	150181
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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